


REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
	3	Production	E Benedict	4 OCT 18

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. MAXIMUM SOLDER TEMPERATURE IS 250 DEG C.
3. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP AND BOTTOM SIDE SMD.
4. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS.
LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER.
MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
5. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
6. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE
BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
7. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD
8. BREAK BOARDS AS A SET. DO NOT BREAK AT THIS LOCATION

APPROVALS		 <div>1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1000 www.linear.com ADI CONFIDENTIAL FOR CUSTOMER USE ONLY</div>		
PCB DES.	EB			
APP ENG.	EB	TITLE: TOP ASSEMBLY DRAWING DEMO CIRCUIT RUGGED I2C SLAVE DEVICE EXTENDER		
		SIZE N/A	IC NO. LTC4331 DEMO CIRCUIT DC2754A	REV. 3
SCALE = NONE		SHT 1 OF 2		